



23rd IEEE International Requirements Engineering Conference

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August 24-28, 2015. Ottawa, Canada

**Requirements *for* the masses.
Requirements *from* the masses.**

RE'15 offers an extensive program of interest to academia, government and industry including three distinguished keynote speakers and three conference days full of papers, panels, posters and demos. A series of exciting tutorials to develop skills in and advance awareness of requirements engineering practices is of particular interest to industry. The main conference is preceded by two days of workshops and the doctoral symposium.

CALL FOR CONTRIBUTIONS

RE'15 invites original submissions of **research papers**, **RE: Next! papers** and **industry papers** in all areas of requirements engineering including elicitation, specification, modeling, analysis, verification and evolution. Categories of **research papers** include Technical Solution papers that describe and validate better solutions to requirements problems, Scientific Evaluation papers that evaluate existing problem situations or proposed solutions by scientific means and Vision papers that explore successes and challenges of requirements practices, or present research roadmaps. **RE: Next!** papers are short communications that describe the current status of ongoing research. **Industry papers** report on the application of requirements engineering techniques in real-world settings, present problems or challenges encountered in practice and report on innovative approaches to requirements engineering practice in industrial or government settings. RE'15 also welcomes submissions for **workshops**, **tutorials**, **panels**, **interactive events**, **poster**, **tool demonstrations** and the **doctoral symposium**.

EXPLORE OTTAWA

Ottawa is the capital of Canada. Placed at the confluence of three rivers, Ottawa offers attractive views, great outdoors, beautiful museums and many other exciting attractions. Ottawa borders Gatineau (Québec), and together they form the National Capital Region, with a multicultural population of approximately 1.2 million people. With more than 1900 technology companies now employing nearly 75,000 people, Ottawa's key industries include wireless, photonics, clean tech, life sciences, aerospace and defence, financial services, healthcare, government, and entertainment. Ottawa is also one of the most educated cities in one of the most educated countries in the world, with the University of Ottawa, a bilingual public research university founded in 1848, which now enrolls well over 40,000 students.

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IMPORTANT DATES in 2015:
 JAN 26 WORKSHOP PROPOSALS
 MAR 02 TUTORIAL PROPOSALS
 MAR 02 PAPER ABSTRACTS
 MAR 09 FULL PAPERS

APR 13 PANEL & INTERACTIVE PROPOSALS
APR 13 DOCTORAL SYMPOSIUM
APR 13 POSTERS & TOOL DEMOS
MAY 18 AUTHOR NOTIFICATION
JUN 19 CAMERA READY

Ottawa
Section

